

1. Features

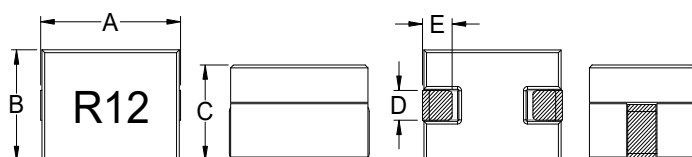
1. Low loss realized with low DCR.
2. High performance realized by metal dust core.
3. Ultra low buzz noise, due to composite construction.
4. 100% Lead(Pb)-Free & Halogen-Free and RoHS compliant.



2. Applications

Commercial applications.

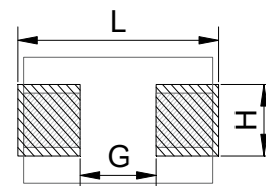
3. Dimensions



A	B	C	D	E
10.60Max	8.00Max	7.00Max	2.10±0.3	2.20±0.3

Unit:mm

Recommend PC Board Pattern



L	G	Hf
11.00	5.30	2.50

Note: 1.PCB layout is referred to standard IPC-7351B

2. The above PCB layout reference only.

3. Recommend solder paste thickness at 0.15mm and above.

4. Part Numbering

SLPI	100807	S	-	R12	M	-	R2905
A	B	C		D	E		F

A: Series

B: Dimension

C: Type

D: Inductance

E: Inductance Tolerance

F: Code

BxC

Standard

R12=0.12uH

M=±20%

DC Resistance, Marking direction cannot decide polarity.

5. Specification

Part Number	Inductance L0A DC (uh)	I rms (A)	I sat (A)Typ		DCR (mΩ)	Mark
		Max	25℃	125℃		
SLPI100807S-R12M-R2905	0.12±20%	61	94	86	0.29±5%	R12
SLPI100807S-R15M-R2905	0.15±20%	61	75	60	0.29±5%	R15
SLPI100807S-R17M-R2905	0.17±20%	61	62	52	0.29±5%	R17
SLPI100807S-R18M-R2905	0.18±20%	61	60	50	0.29±5%	R18
SLPI100807S-R22M-R2905	0.22±20%	61	50	40	0.29±5%	R22
SLPI100807S-R27M-R2905	0.27±20%	61	41	33	0.29±5%	R27
SLPI100807S-R30M-R2905	0.30±20%	61	35	30	0.29±5%	R30
SLPI100807S-R33M-R2905	0.33±20%	61	33	26.5	0.29±5%	R33
SLPI100807S-R39M-R2905	0.39±20%	61	28	22.5	0.29±5%	R39
SLPI100807S-R47M-R2905	0.47±20%	61	23.5	19	0.29±5%	R47

Note:

1. Test frequency : Ls : 100KHz /0.1V.
2. All test data referenced to 20℃ ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40℃
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125℃under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. I rms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components.
Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of I rms and Isat.